

### C Atomic Order Doping at Si/Si<sub>1-x</sub>Ge<sub>x</sub>/Si Heterointerface and Improvement of Thermal Stability

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High performance SiGe-based heterodevices require high Ge fraction and it is essential to suppress the intermixing between Si and Ge at Si/SiGe heterointerface. It was reported that C introduction into SiGe heterostructure is effective to control lattice strain and B diffusion [1]. In our previous work, it was reported that the intermixing between Si and Ge at Si/Ge heterointerface during heat treatment is suppressed by the existence of C atom at the interface [2]. In the present work, C atomic order doping at Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si heterointerface and the redistribution of Ge fraction during heat treatment is investigated.

The 3nm-thick Si/5nm-thick strained Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si heterostructure was epitaxially grown at 450-500°C by low pressure chemical vapor deposition using the SiH<sub>4</sub>-GeH<sub>4</sub> gas system [3]. The atomic layer order doping of C to the Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si heterointerface was performed at 400-500°C by SiH<sub>3</sub>CH<sub>3</sub> reaction [4]. Some of the samples were heat-treated at 700-750°C for 1hour in H<sub>2</sub> atmosphere. C atom amount at Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si heterointerface was evaluated by repetition of 0.6-1.3nm-thick wet etching and X-ray photoelectron spectroscopy(XPS) measurement. The distribution of Ge fraction in Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si heterostructure was also evaluated by the above depth profile measurement method and X-ray diffraction(XRD).

At the Si/Si<sub>0.5</sub>Ge<sub>0.5</sub> heterointerface (surface side), the C atom amount is 1.1x10<sup>14</sup>cm<sup>-2</sup> and almost equal to the initial amount (9.0x10<sup>13</sup>cm<sup>-2</sup>) before the Si capping deposition. However, at the Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si heterointerface (substrate side), the C atom amount is 1.6x10<sup>13</sup>cm<sup>-2</sup> and smaller than the initial amount (5.8x10<sup>13</sup>cm<sup>-2</sup>) before the Si<sub>0.5</sub>Ge<sub>0.5</sub> deposition. Depth dependence of Ge 3d XPS intensity of Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si and Si/Si<sub>0.5</sub>Ge<sub>0.494</sub>C<sub>0.006</sub>/Si heterostructures before and after heat treatment at 700°C is shown in Fig. 1. The redistribution of Ge fraction due to heat treatment is scarcely influenced by C addition.

XRD rocking curves of Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si and Si/C/Si<sub>0.5</sub>Ge<sub>0.5</sub>/C/Si heterostructures are shown in Fig. 2. The curve of Si/C/Si<sub>0.5</sub>Ge<sub>0.5</sub>/C/Si is nearly the same as that of Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si, in other words, Si/C/Si<sub>0.5</sub>Ge<sub>0.5</sub>/C/Si heterostructure has similar strain as Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si. The Ge fraction profile in Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si and Si/C/Si<sub>0.5</sub>Ge<sub>0.5</sub>/C/Si are shown in Fig. 3. It is found that the redistribution of Ge fraction in Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si during heat treatment is suppressed by C incorporation. It is considered that this interface strain is dispersed by C incorporation.

#### References

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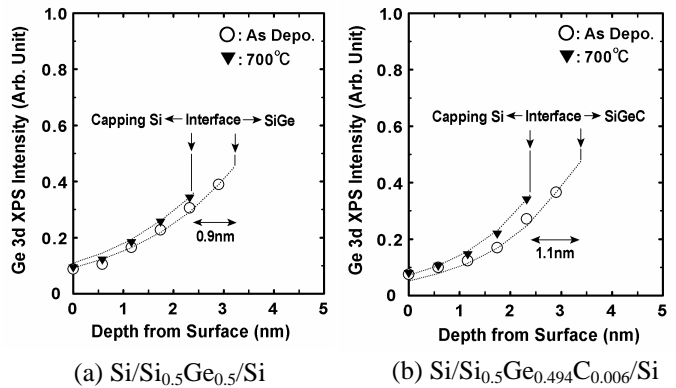


Fig. 1. Depth dependence of Ge 3d XPS intensity from Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si and Si/Si<sub>0.5</sub>Ge<sub>0.494</sub>C<sub>0.006</sub>/Si heterostructures before and after heat treatment at 700°C for 1hour in H<sub>2</sub> atmosphere. Interface positions shown by arrows are determined by XRD measurement.

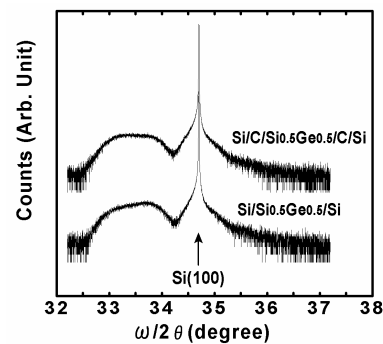


Fig. 2. XRD rocking curves of Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si and Si/C/Si<sub>0.5</sub>Ge<sub>0.5</sub>/C/Si heterostructures.

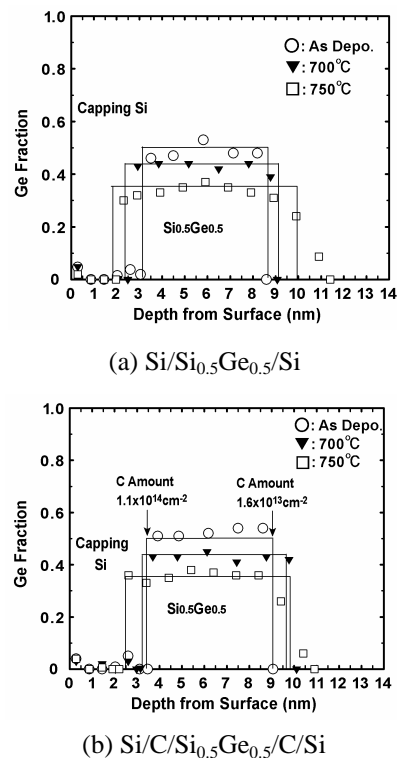


Fig. 3. Estimated Ge distribution of Si/Si<sub>0.5</sub>Ge<sub>0.5</sub>/Si and Si/C/Si<sub>0.5</sub>Ge<sub>0.5</sub>/C/Si heterostructures before and after heat treatment. Solid lines are determined by XRD measurement.